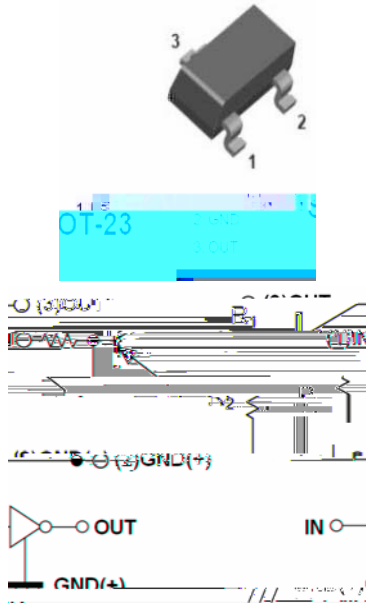


PNP Digital Transistors (Built-in Resistors)



Features

- ‘ Moisture sensitivity level 1
- fl Halogen free and RoHS compliant
- fl Surface mount package ideally suited for automatic insertion

Application

- ‘ Signal amplification
- fl Switching circuit

Mechanical data

- ‘ **Package** SOT-23
- fl **Terminals** Tin plated leads, solderable per J-STD-002 and JESD22-B102

Maximum Ratings ($T_a=25$ Unless otherwise specified)

Item	Symbol	Unit	Conditions	Value
Device marking code				AB
Supply voltage	V_{CC}	V		-50
Input voltage	V_{IN}	V		-40 to +10
Output current	I_o	mA		-100
Power dissipation	P_D	mW		200
Junction temperature	T_J			-55 to +150
Storage temperature	T_{STG}			-55 to +150



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Electrical Characteristics (T_a=25 Unless otherwise specified)

Item	Symbol	Unit	Conditions	Min	Typ	Max
Input voltage	V _{I(off)}	V	V _{CC} =-5V, I _O =-100uA	-0.5		
	V _{I(on)}	V	V _O =-0.3V, I _O =-1mA			-3.0
Output voltage	V _{O(on)}	V	I _O / I _I = -5mA / -0.25mA			-0.3
Input current	I _I	mA	V _I =-5V			-0.15
Output current	I _{O(off)}	uA	V _{CC}			



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Characteristics

Fig. 1 - DC Current Gain Characteristics

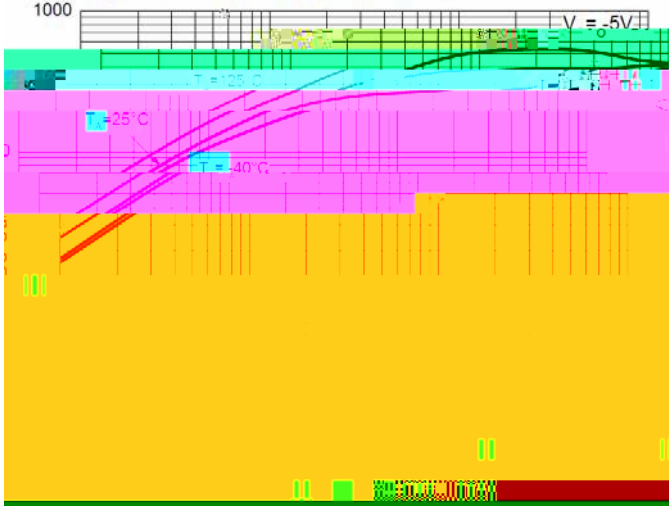


Fig. 2 - Input Voltage (on) Characteristics

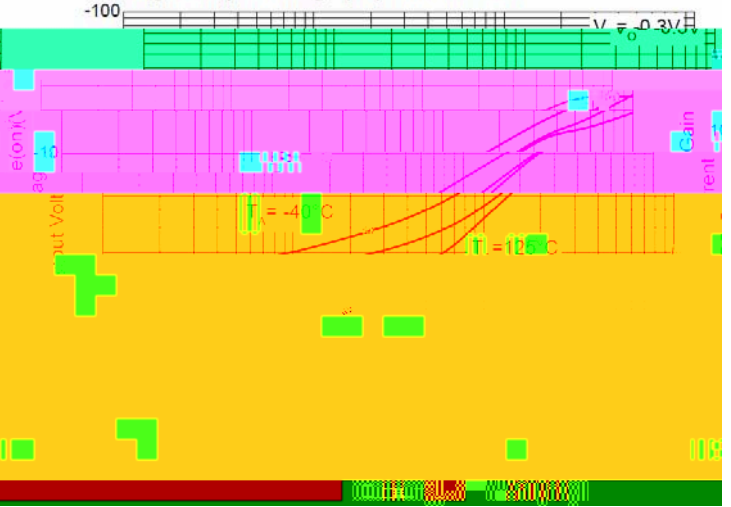


Fig. 3 - Input Voltage (off) Characteristics

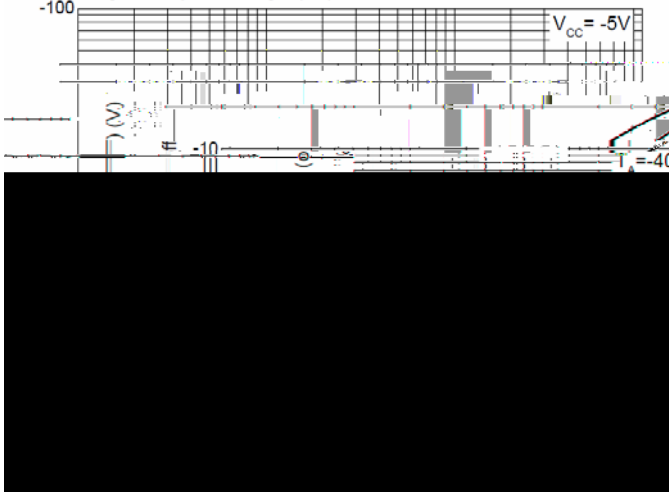
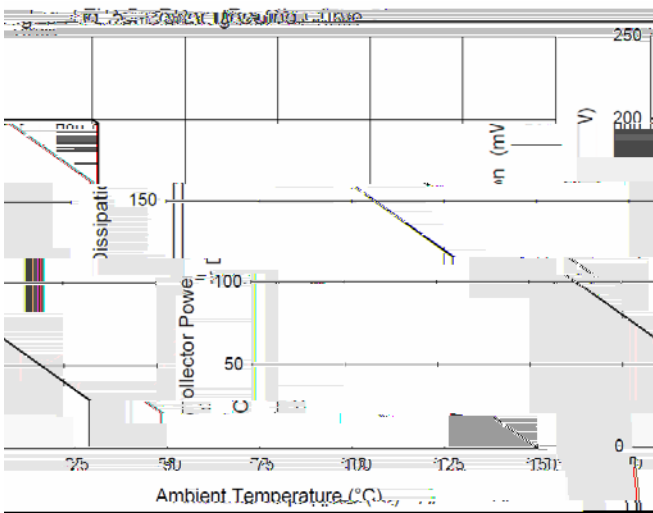
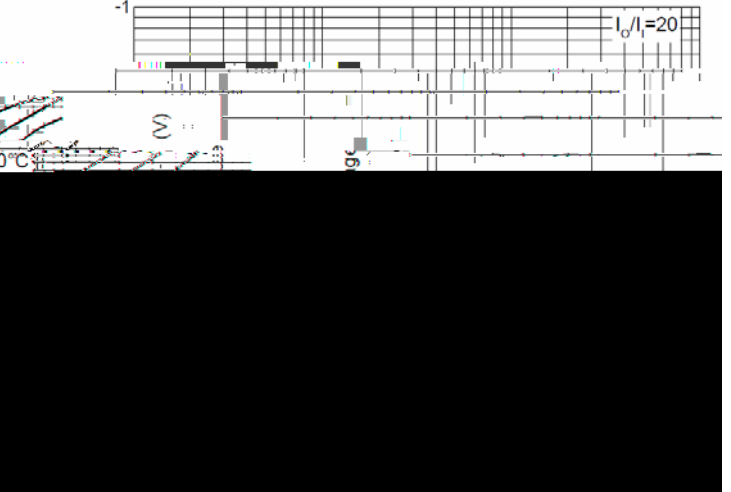


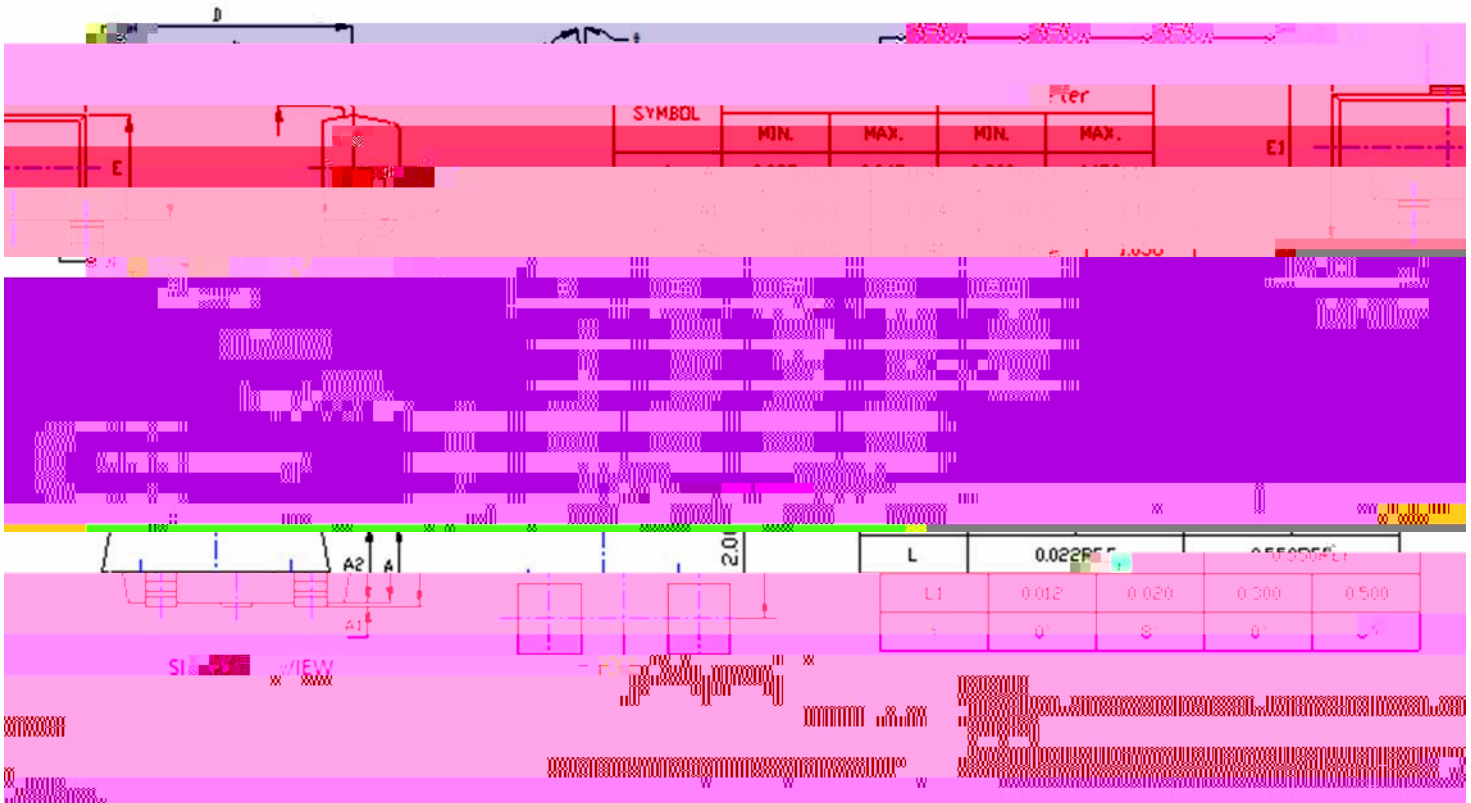
Fig. 4 - Output Voltage Characteristics





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Outline Dimensions



Note:

1. All dimensions are in millimeters (mm) unless otherwise specified.

[所有尺寸均以毫米为单位，除非另有说明]

2. General tolerances: ±0.10mm unless otherwise specified.

[通用公差为±0.10mm，除非另有说明]

3. Dimensions and tolerance per ASME Y14.5M-2018.

[尺寸和公差遵循 ASME Y14.5M-2018 标准]

Dimension b does not include mold flash and burrs but only the maximum

exceed 0.15 mm in maximum.

[所有尺寸均不包括毛刺和浇口残留。毛刺与浇口残留的尺寸最大不得超过 0.15mm]

Dimension b does not include a maximum protrusion of maximum 0.100 mm per side.

[尺寸b不包括单边最大0.100 mm的引脚凸出部分]

Dimensions exclude mold flash, lead flash, protrusions and burrs but include the maximum allowable mold mismatch.

[尺寸是封装体的外部极限尺寸，不包括包转溢料、引脚溢料、凸出部分以及胶体毛刺，但是包含了封装错位的最大尺寸]

Formed leads and line donor with respect to one another within a maximum of 0.100 mm relative to the seating plane.

[成型的管脚应为同一平面，共面性最大为0.1mm]

★ Dimension b size.

[★ 标记为关键尺寸]



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